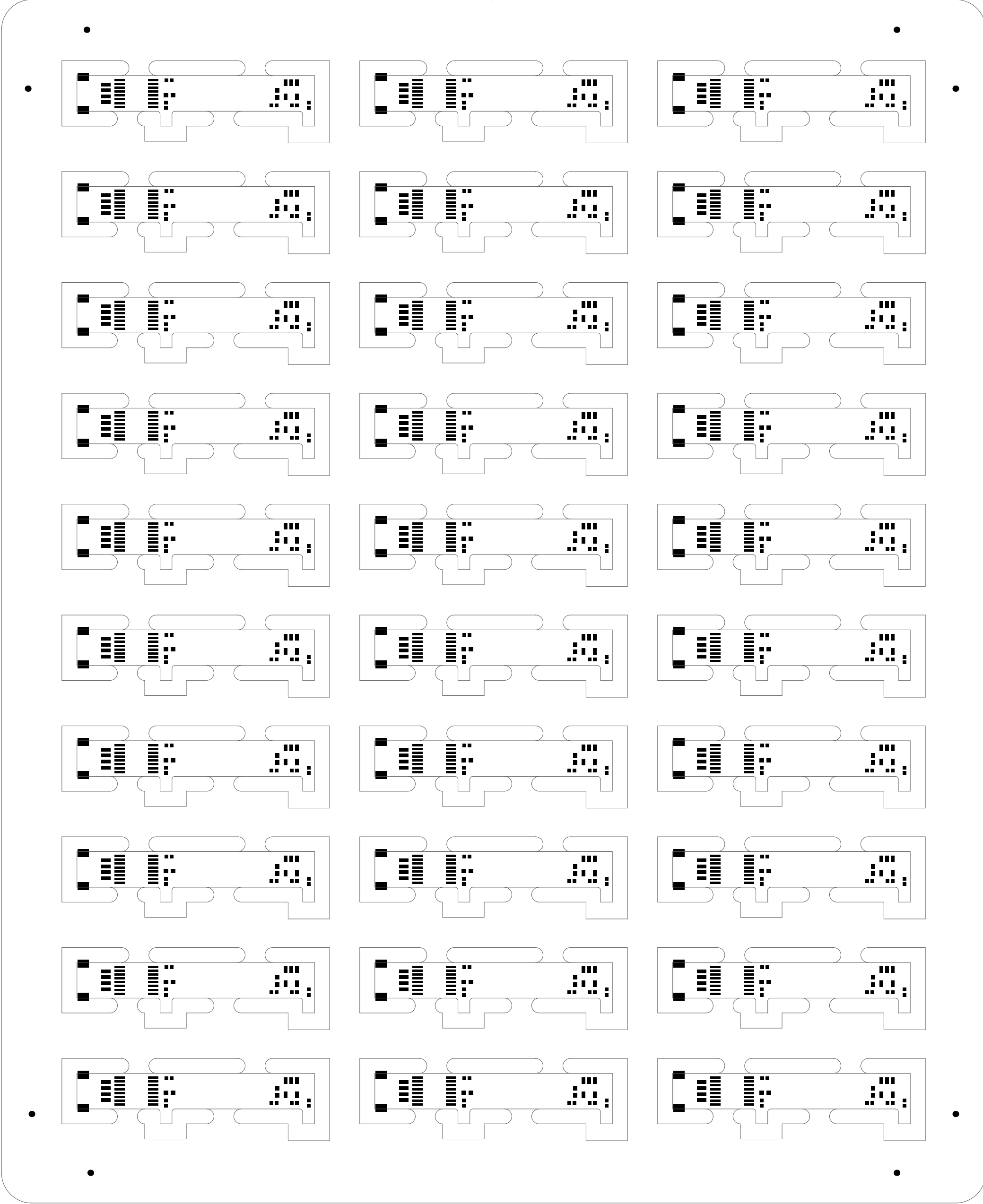


MAXIMUM PANEL SIZE



NOTES:
1) PADS ARE 1:1 REDUCTION TO BE SPECIFIED BY THE ASSEMBLER
2) VIEW ON SQUEEGEE SIDE DO NOT MIRROR
3) STENCIL TYPE AND FRAMING TO BE SPECIFIED BY THE ASSEMBLER
4) INDICATED FRAME REPRESENTS MAXIMUM PANEL SIZE AND MUST BE CENTERED ON THE SOLDER STENCIL

TITLE
SMP PCB
TOP SIDE SOLDER STENCIL

PLOTFILE	SMP [Panel]	GTP	EDM	-	-	19/11/2024	01	-	DWG NUMBER	-	PCB VER	SHEET NO.
			DRAWN	CHECKED	APPROVED	DATE	DOC REV.	ECR NO.	SOURCE	SMP [Panel].PcbDoc	11.00	SHEET 1 OF 2



<div><div><div>GENTICK</div><div>ELECTRONICS</div><div>EXPERTS IN TELEMETRY SYSTEMS</div></div><div></div></div>			<div>NOTES:</div> <div>1) PADS ARE 1:1 REDUCTION TO BE SPECIFIED BY THE ASSEMBLER</div> <div>2) VIEW ON SQUEEGEE SIDE DO NOT MIRROR</div> <div>3) STENCIL TYPE AND FRAMING TO BE SPECIFIED BY THE ASSEMBLER</div> <div>4) INDICATED FRAME REPRESENTS MAXIMIUM PANEL SIZE AND MUST BE CENTERED ON THE SOLDER STENCIL</div>						<div>TITLE</div> <div>SMP PCB</div> <div>BOTTOM SIDE SOLDER STENCIL</div>			
			EDM	-	-	19/11/2024	01	-	DWG NUMBER	-	PCB VER	SHEET NO.
			PLOTFILE	SMP [Panel]	GBP	DRAWN	CHECKED	APPROVED	DATE	DOC REV.	ECR NO.	SOURCE